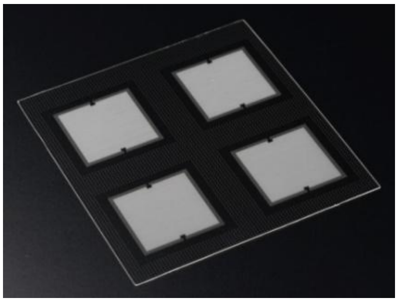
EBINAX株式会社
EBINAX Co., Ltd

TGV Technology

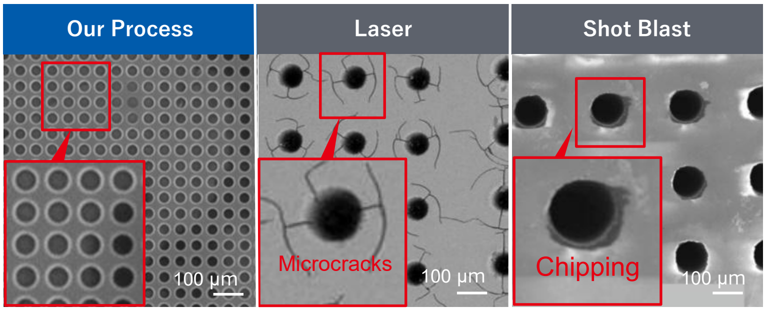
Realization of high-density and high-frequency device support

Features

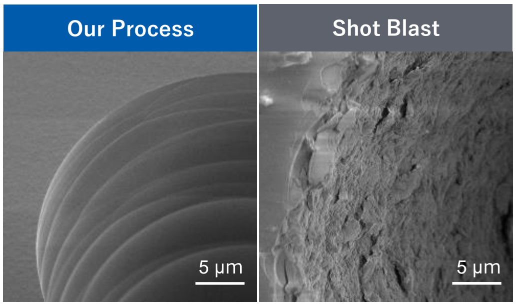
- **Dense microholes without microcracks**
- **Enables wiring to substrates with through-holes**
- **Providing integrated support for all processes starting from material procurement**



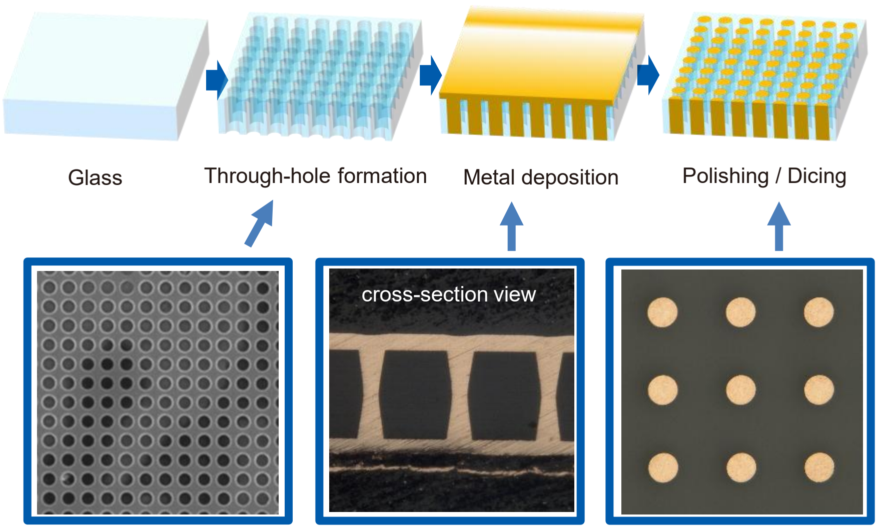
High-density microhole processing without cracks or chips.



The inside walls of our microholes have a roughness of Ra≦0.08μm.

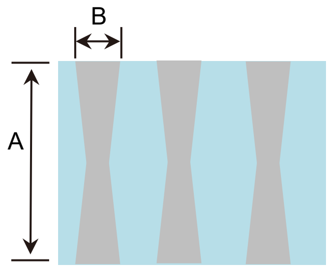


Process Flow



Design

Size	4 inch <
Tickness	100-1000 µm
Aspect ratio	up to 10



Material

Alkali-free glass
Borosilicate glass
Quartz

EBINAX Co.,Ltd.
5-22-13 Higashikojiya, Ota-ku, Tokyo 144-0033, Japan/ URL: https://ebinax.com/